

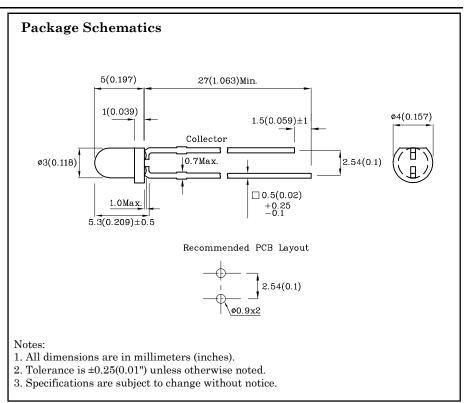
Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- RoHS Compliant



Part Number: XRNI30W-1

Phototransistor



Electrical / Optical Characteristics at TA=25°C

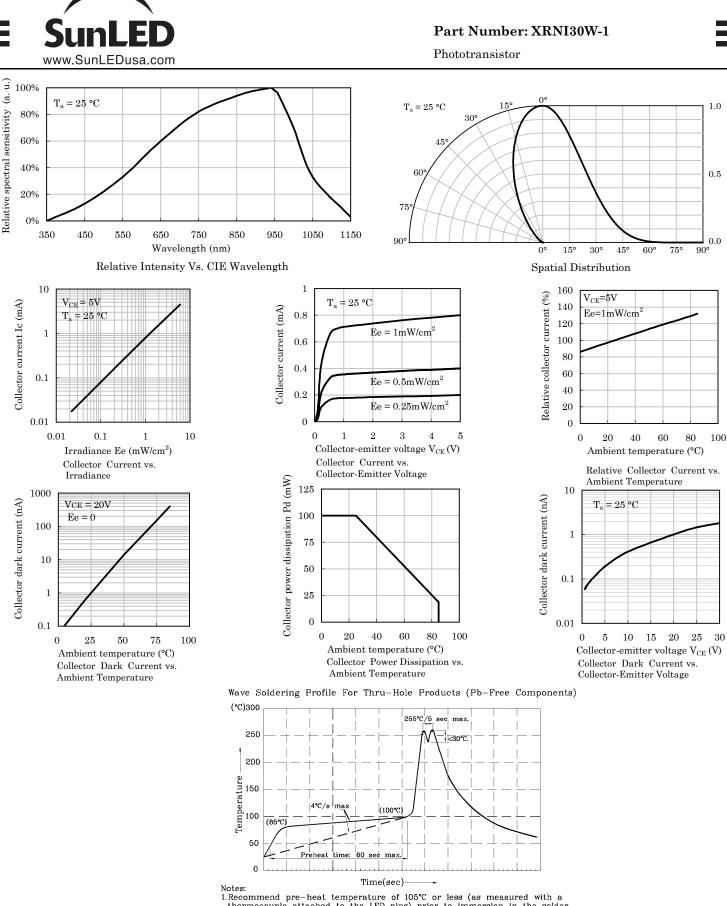
Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Condiction
VBR CEO	Collector-to-Emitter Breakdown Voltage	30	-	-	V	$\begin{split} I_c &= 100 \mu A \\ E_e &= 0 m W/cm^2 \end{split}$
VBR ECO	Emitter-to-Collector Breakdown Voltage	5	-	-	v	$\begin{split} I_{\text{E}} &= 100 \mu A \\ E_{\text{e}} &= 0 \text{mW/cm}^2 \end{split}$
VCE(SAT)	Collector-to-Emitter Saturation Voltage	-	-	0.8	V	$I_{\rm C} = 2mA \\ E_{\rm e} = 20mW/cm^2$
ICEO	Collector Dark Current	-	-	100	nA	$\label{eq:Vce} \begin{split} V_{CE} &= 10V\\ E_e &= 0mW/cm^2 \end{split}$
TR	Rise Time (10% to 90%)	-	15	-	μs	$V_{CE} = 5V$ $I_C = 1mA$
$\mathrm{T}\mathrm{F}$	Fall Time (90% to 10%)	-	15	-	μs	$R_{L} = 1 M \Omega$ $R_{L} = 1 K \Omega$
I(ON)	On State Collector Current	0.3	0.8	-	mA	$V_{\rm CE} = 5V$ $E_{\rm e} = 1 \text{mW/cm}^2$ $\lambda = 940 \text{nm}$
$\lambda_{0.1}$	Range of spectral bandwidth	420	-	1120	nm	-
λ_{p}	Wavelength of peak sensitivity	-	940	-	nm	-
$2\theta 1/2$	Angle of half sensitivity	-	50	-	deg	-

Absolute Maximum Ratings at TA=25°C

Parameter	Maximum Ratings		
Collector-to-Emitter Voltage	30V		
Emitter-to-Collector Voltage	$5\mathrm{V}$		
Power Dissipation at (or below) 25°C Free Air Temperature	$100 \mathrm{mW}$		
Operating / Storage Temperature Range	-40 ~ +85°C		
Lead Solder Temperature (>5mm for 5sec)	260°C		

A Relative Humidity between 40% and 60% is recommended in

ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)
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Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

(5 sec max).

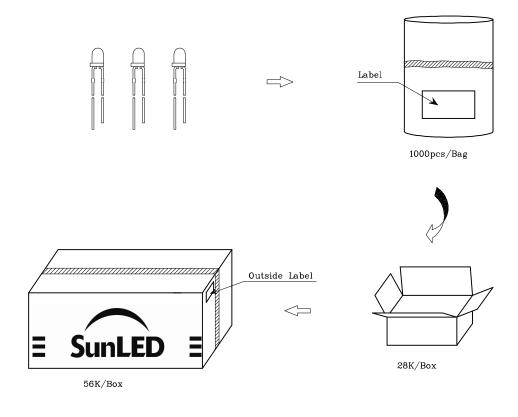
3.Do not apply stress to the epoxy resin while the temperature is above $85^\circ\!C.$ 4. Fixtures should not incur stress on the component when mounting and during soldering process.
 5. SAC 305 solder alloy is recommended.
 6. No more than one wave soldering pass.

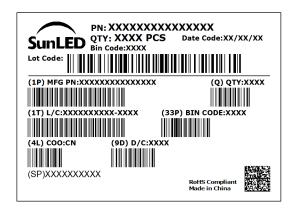
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PACKING & LABEL SPECIFICATIONS





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